

1. Product Overview

WB3L is a low-power embedded Wi-Fi module that Tuya has developed. It consists of a highly integrated RF chip (BK7231T) and several peripheral components, with an embedded Wi-Fi network protocol stack and robust library functions. WB3L is embedded with a low-power Arm Cortex-M4 microcontroller unit (MCU), 2 MB flash memory, 256 KB static random-access memory (SRAM), and extensive peripherals.

WB3L is an RTOS platform that integrates all function libraries of the Wi-Fi MAC and TCP/IP protocols. You can develop embedded Wi-Fi products as required.

1.1 Features

- ✧ Embedded low-power 32-bit CPU, which can also function as an application processor
 - Clock rate: 120 MHz
- ✧ Working voltage: 3.0 V to 3.6 V
- ✧ Peripherals: eight GPIOs
- ✧ Wi-Fi connectivity
 - 802.11b/g/n
 - Channels 1 to 14 at 2.4 GHz
 - WPA and WPA2 security modes
 - Up to +20dBm output power in 802.11b mode
 - STA, AP, and STA+AP working modes

- EZ and AP net pairing modes for Android and iOS devices
 - Onboard PCB antenna with a gain of 1.2 dBi
 - Working temperature: -20°C to $+105^{\circ}\text{C}$
- ✧ Bluetooth
- Support for Bluetooth 4.0
 - Maximum output power of $+10\text{ dBm}$
 - Onboard PCB antenna with a gain of 1.2 dBi

1.2 Application Scenarios

- ✧ Intelligent building
- ✧ Smart household and home appliances
- ✧ Smart socket and light
- ✧ Industrial wireless control
- ✧ Baby monitor
- ✧ Network camera
- ✧ Intelligent bus

Change History

No.	Date	Change Description	Version After Change
1	2019-11-17	This is the first release.	1.0.0

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2. Module Interfaces

2.1 Dimensions and Footprint

WB3L has two rows of pins with a 2 ± 0.1 mm pin spacing.

The WB3L dimensions (H x W x D) are 2.8 ± 0.15 mm x 16 ± 0.35 mm x 24 ± 0.35 mm. Figure 2-1 shows the WB3L front and rear views.

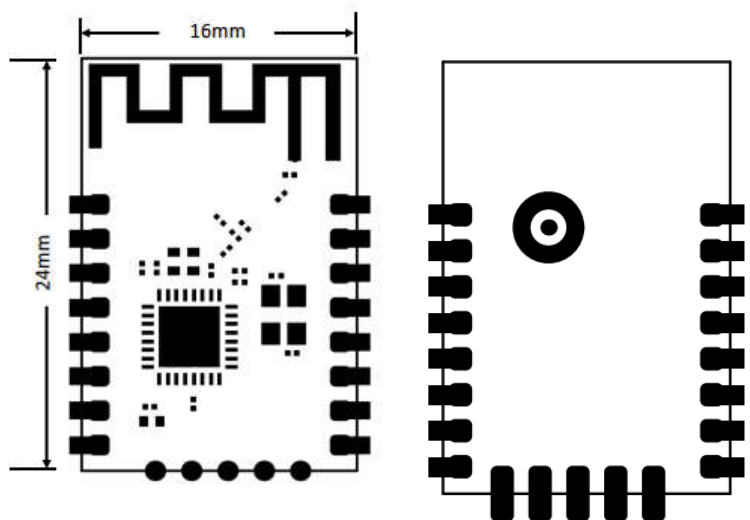


Figure 2-1 WB3L front and rear views

2.2 Interface Pin Definition

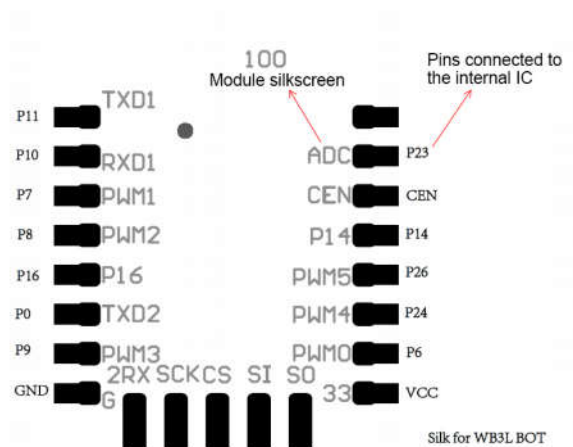


Table 2-1 WB3L interface pins

Pin No.	Symbol	I/O Type	Function
1	RST	I/O	Reset pin, which is disconnected
2	ADC	AI	ADC pin, which is connected to the P23 pin on the internal IC
3	EN	Input	Module enabling pin, which is connected to 3.3 V for normal use
4	P14	I/O	Common I/O pin, which is connected to the P14 pin on the internal IC
5	PWM5	I/O	Hardware PWM pin, which is connected to the P26 pin on the internal IC
6	PWM4	I/O	Hardware PWM pin, which is connected to the P24 pin on the internal IC
7	PWM0	I/O	Hardware PWM pin, which is connected to the P6 pin on the internal IC
8	VCC	P	Power supply pin (3.3 V)
9	GND	P	Ground pin
10	PWM3	I/O	Hardware PWM pin, which is connected to the P9 pin on the internal IC
11	TXD2	I/O	UART2_TX, which is connected to the P0 pin on the internal IC
12	P16	I/O	Common I/O pin, which is connected to the P16 pin on the internal IC
13	PWM2	I/O	Hardware PWM pin, which is connected to the P8 pin on the internal IC
14	PWM1	I/O	Hardware PWM pin, which is connected to the P7 pin on the internal IC
15	RXD1	I/O	Serial interface receiving pin (UART_RX), which is connected to the P10 pin on the internal IC
16	TXD1	I/O	Serial interface transmission pin (UART_TX), which is connected to the P11 pin on the internal IC

Note:

P indicates a power supply pin, **I/O** indicates an input/output pin, and **AI** indicates an analog input pin.

2.3 Test Pin Definition

Table 2-2 WB3L test pins

Pin No.	Symbol	I/O Type	Function
TP6	U2_RXD	I/O	UART2_RX, which is connected to the P1 pin on the internal IC
TP2	F_SCK	I/O	Clock pin when data is downloaded from the flash memory, which is connected to the P20 pin on the internal IC
TP3	F_CSN	I/O	Command enabling pin when data is downloaded from the flash memory, which is connected to the P21 pin on the internal IC
TP4	F_SI	I/O	Data input pin when data is downloaded from the flash memory, which is connected to the P22 pin on the internal IC
TP5	F_SO	I/O	Data output pin when data is downloaded from the flash memory, which is connected to the P23 pin on the internal IC

Note:

Test pins are not recommended.

3. Electrical Parameters

3.1 Absolute Electrical Parameters

Table 3-1 Absolute electrical parameters

Parameter	Description	Minimum Value	Maximum Value	Unit
Ts	Storage	−40	105	°C

Parameter	Description	Minimum Value	Maximum Value	Unit
	temperature			
VBAT	Power supply voltage	3.0	3.6	V
Static electricity voltage (human body model)	Tamb = 25°C	N/A	2	kV
Static electricity voltage (machine model)	Tamb = 25°C	N/A	0.5	kV

3.2 Working Conditions

Table 3-2 Normal working conditions

Parameter	Description	Minimum Value	Typical Value	Maximum Value	Unit
Ta	Working temperature	−40	N/A	105	°C
VBAT	Power supply voltage	3.0	3.3	3.6	V
V _{IL}	I/O low-level input	−0.3	N/A	VCC x 0.25	V
V _{IH}	I/O high-level input	VCC x 0.75	N/A	VCC	V
V _{OL}	I/O low-level output	N/A	N/A	VCC x 0.1	V
V _{OH}	I/O high-level output	VCC x 0.8	N/A	VCC	V
I _{max}	I/O drive current	N/A	N/A	12	mA

3.3 RF Current Consumption

Table 3-3 Current consumption during constant transmission and receiving

Working Status	Parameter			Typical Value	Maximum Value	Unit
	Mode	Rate	TX Power/Receiving			
TX	802.11b	11 Mbit/s	+17 dBm	295	354	mA
	802.11g	54 Mbit/s	+13.5 dBm	266	300	mA
	802.11n	MCS7	+13 dBm	260	290	mA
RX	802.11b	11 Mbit/s	Constant receiving	98	100	mA
	802.11g	54 Mbit/s	Constant receiving	98	100	mA
	802.11n	MCS7	Constant receiving	98	100	mA

3.4 Working Current

Table 3-4 Working current

Working Mode	Working Status (Ta = 25°C)	Average Value	Maximum Value	Unit
EZ	The module is in EZ mode, and the Wi-Fi indicator blinks quickly.	98	100	mA
AP	The module is in AP mode, and the Wi-Fi indicator blinks slowly.	53	125	mA
Connected	The module is connected to the network, and the Wi-Fi indicator is steady on.	60	170	mA
Disconnected	The module is disconnected from the network, and the Wi-Fi indicator is steady off.	40	88	mA

4. RF Features

4.1 Basic RF Features

Table 4-1 Basic RF features

Parameter	Description
Frequency band	BT:2.400 GHz to 2.4835 GHz WIFI:2.412 GHz to 2.484 GHz
Wi-Fi standard	IEEE 802.11b/g/n (channels 1 to 14, Ch1-11 for US/CA, Ch1-13 for EU/CN)
BT standard	BT 4.0
Data transmission rate	802.11b: 1, 2, 5.5, or 11 (Mbit/s) 802.11g: 6, 9, 12, 18, 24, 36, 48, or 54 (Mbit/s) 802.11n: HT20 MCS0 to MCS7 HT40 MCS0 to MCS7
Antenna type	PCB antenna with a gain of 1.2 dBi

4.2 TX Performance

Table 4-2 Performance during constant transmission

Parameter		Minimum Value	Typical Value	Maximum Value	Unit
Average RF output power, 802.11b CCK mode	11 Mbit/s	N/A	16	N/A	dBm
Average RF output power, 802.11g OFDM mode	54 Mbit/s	N/A	14	N/A	dBm
Average RF output power, 802.11n OFDM mode	MCS7	N/A	12	N/A	dBm
Frequency error		-10	N/A	+10	ppm

4.3 RX Performance

Table 4-3 RX sensitivity

Parameter		Minimum Value	Typical Value	Maximum Value	Unit
PER < 8%, 802.11b DSSS mode	11 Mbit/s	N/A	−85	N/A	dBm
PER < 10%, 802.11g OFDM mode	54 Mbit/s	N/A	−72	N/A	dBm
PER < 10%, 802.11n OFDM mode	MCS7	N/A	−68	N/A	dBm

5. Antenna Information

5.1 Antenna Type

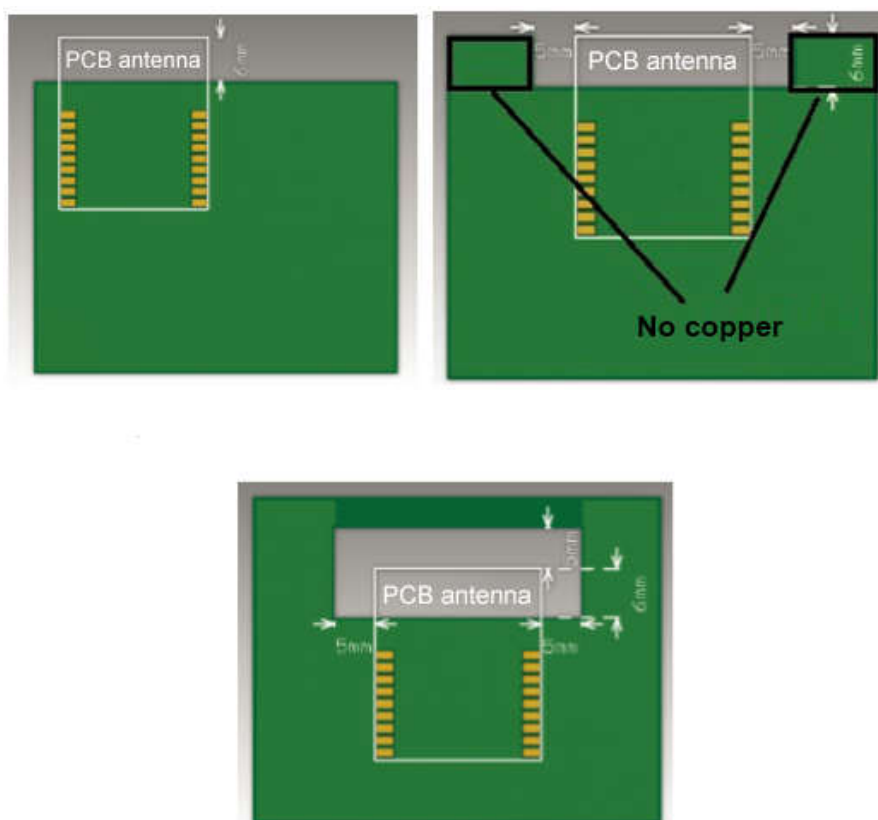
WB3L uses an onboard PCB antenna.

5.2 Antenna Interference Reduction

To ensure optimal Wi-Fi performance when the Wi-Fi module uses an onboard PCB antenna, it is recommended that the antenna be at least 15 mm away from other metal parts.

To prevent adverse impact on the antenna radiation performance, avoid copper or traces along the antenna area on the PCB.

For details about the onboard PCB antenna area on WB3L, see Figure 6-1.



6. Packaging Information and Production Instructions

6.1 Mechanical Dimensions

The PCB dimensions (H x W x D) are 2.8 ± 0.15 mm x 16 ± 0.35 mm x 24 ± 0.35 mm.

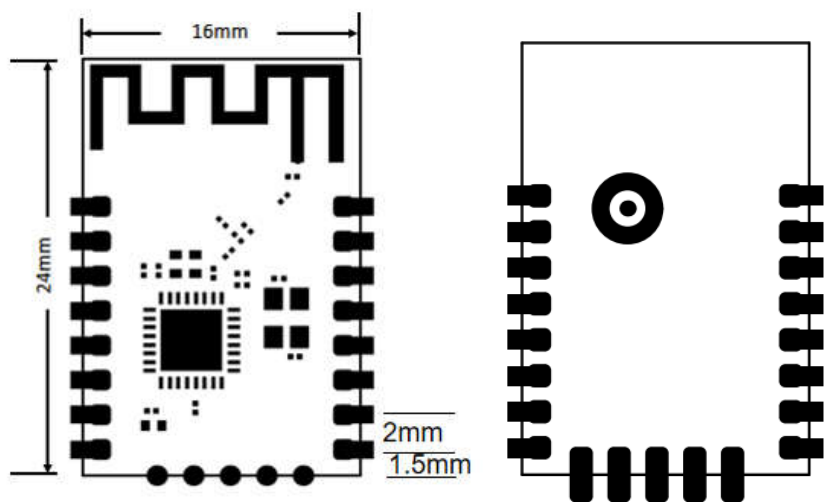


Figure 6-1 WB3L mechanical dimensions

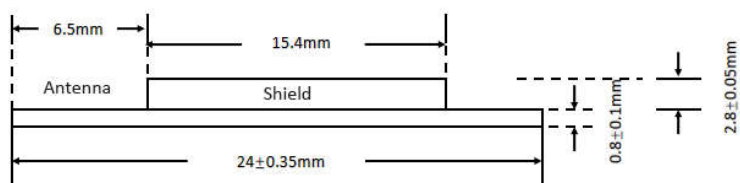


Figure 6-2 Side view

6.2 Recommended PCB Layout

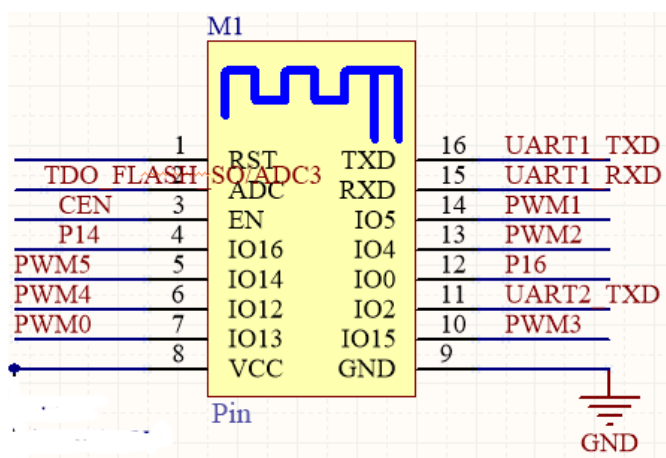


Figure 6-3 WB3L pins

WB3L can be mounted onto a PCB by using an SMT placement machine or through-hole mounted onto the PCB through a pin header. Figure 6-4 shows the pin header dimensions.

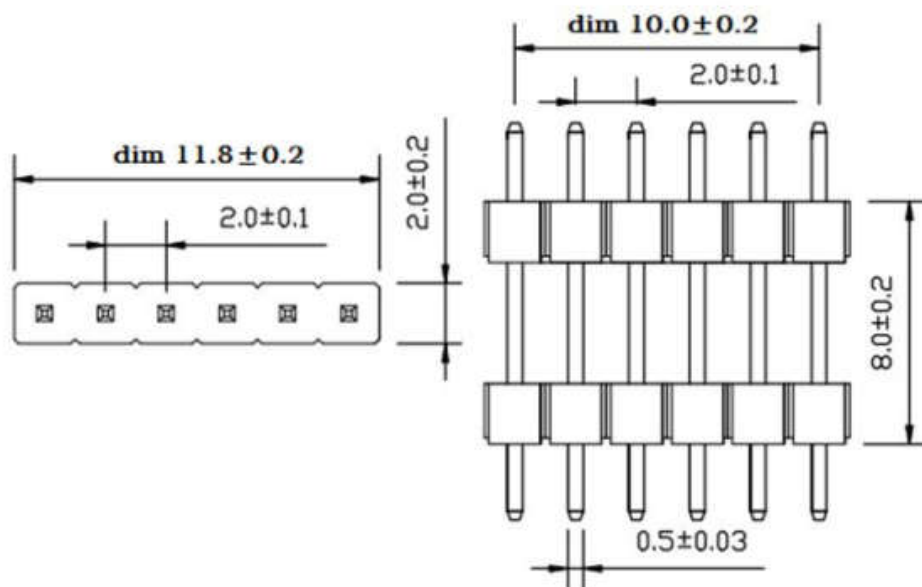


Figure 6-4 WB3L pin header dimensions

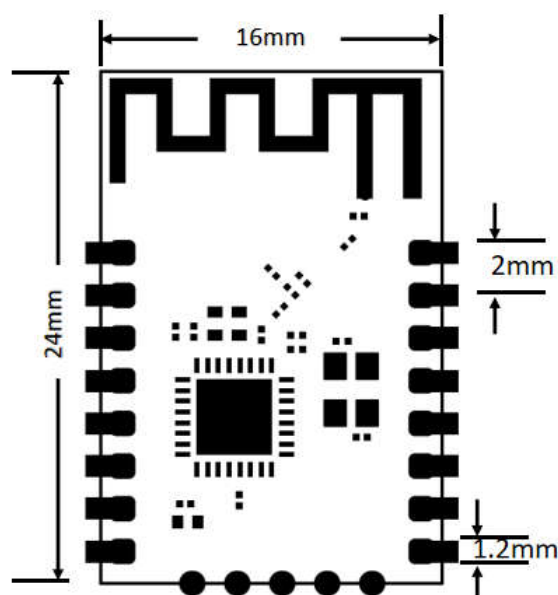


Figure 6-5 Layout of the PCB to which WB3L applies

6.3 Production Instructions

1. Use an SMT placement machine to mount the stamp hole module that Tuya produces onto the PCB within 24 hours after the module is unpacked and the firmware is burned. If not, vacuum pack the module again. Bake the module before mounting it onto the PCB.
 - (1) SMT placement equipment
 - i. Reflow soldering machine
 - ii. Automated optical inspection (AOI) equipment
 - iii. Nozzle with a 6 mm to 8 mm diameter
 - (2) Baking equipment
 - i. Cabinet oven
 - ii. Anti-static heat-resistant trays
 - iii. Anti-static heat-resistant gloves
2. Storage conditions for a delivered module are as follows:
 - (1) The moisture-proof bag is placed in an environment where the temperature is below 30°C and the relative humidity is lower than 70%.
 - (2) The shelf life of a dry-packaged product is six months from the date when the product is packaged and sealed.
 - (3) The package contains a humidity indicator card (HIC).

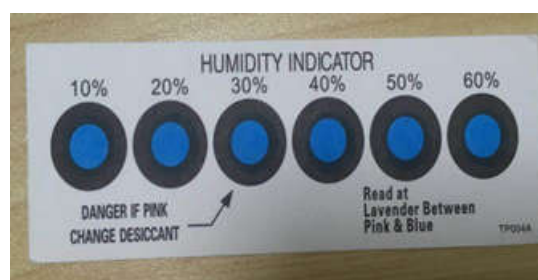


Figure 6-6 HIC for WB3L

3. Bake a module based on HIC status as follows when you unpack the module package:
 - (1) If the 30%, 40%, and 50% circles are blue, bake the module for 2 consecutive hours.

- (2) If the 30% circle is pink, bake the module for 4 consecutive hours.
 - (3) If the 30% and 40% circles are pink, bake the module for 6 consecutive hours.
 - (4) If the 30%, 40%, and 50% circles are pink, bake the module for 12 consecutive hours.
4. Baking settings:
 - (1) Baking temperature: $125\pm5^{\circ}\text{C}$
 - (2) Alarm temperature: 130°C
 - (3) SMT placement ready temperature after natural cooling: $< 36^{\circ}\text{C}$
 - (4) Number of drying times: 1
 - (5) Rebaking condition: The module is not soldered within 12 hours after baking.
5. Do not use SMT to process modules that have been unpacked for over three months. Electroless nickel immersion gold (ENIG) is used for the PCBs. If the solder pads are exposed to the air for over three months, they will be oxidized severely and dry joints or solder skips may occur. Tuya is not liable for such problems and consequences.
6. Before SMT placement, take electrostatic discharge (ESD) protective measures.
7. To reduce the reflow defect rate, draw 10% of the products for visual inspection and AOI before first SMT placement to determine a proper oven temperature and component placement method. Draw 5 to 10 modules every hour from subsequent batches for visual inspection and AOI.

6.4 Recommended Oven Temperature Curve

Perform SMT placement based on the following reflow oven temperature curve. The highest temperature is 245°C .

Refer to IPC/JEDEC standard; Peak Temperature: <245°C; Number of Times: ≤2 times;

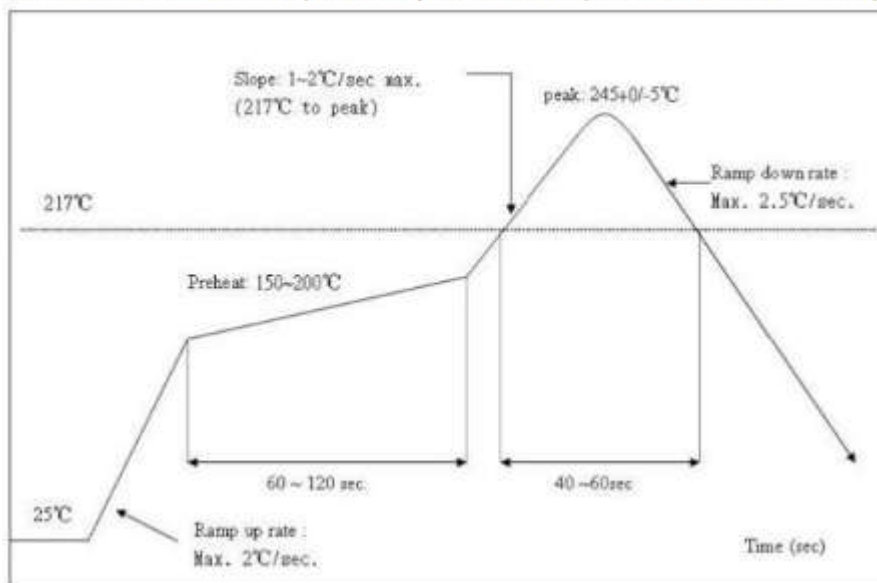


Figure 6-7 Oven temperature curve

6.5 Storage Conditions

	CAUTION This bag contains MOISTURE-SENSITIVE DEVICES	LEVEL <div style="border: 1px solid black; padding: 5px; display: inline-block;"> 3 </div>
If Blank, see adjacent bar code label		
1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH)		
2. Peak package body temperature: <u>260</u> °C <small style="display: block; text-align: right;">If Blank, see adjacent bar code label</small>		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must		
a) Mounted within: <u>168</u> hrs. of factory conditions <small style="display: block; text-align: right;">If Blank, see adjacent bar code label</small>		
≤ 30°C/60%RH, OR		
b) Stored at <10% RH		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card is > 10% when read at 23 ± 5°C		
b) 3a or 3b not met.		
5. If baking is required, devices may be baked for 48 hrs. at 125 ± 5°C		
Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure		
Bag Seal Date: _____ <small style="display: block; text-align: right;">If Blank, see adjacent bar code label</small>		
Note: Level and body temperature defined by IPC/JEDEC J-STD-020		

7. MOQ and Packing Information

MOQ and packing information				
Product Model	MOQ	Packing Method	Number of Modules in Each Reel Pack	Number of Reel Packs in Each Box
WB3L	4000	Carrier tape and reel packing	1000	4

Appendix: Statement

Federal Communications Commission (FCC) Declaration of Conformity

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Radiation Exposure Statement

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled rolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator and your body.

Important Note

This radio module must not be installed to co-locate and operating simultaneously with other radios in host system except in accordance with FCC multi-transmitter product procedures. Additional testing and equipment authorization may be required to operating simultaneously with other radio.

The availability of some specific channels and/or operational frequency bands are country dependent and are firmware programmed at the factory to match the intended destination. The firmware setting is not accessible by the end user.

The host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by the modular transmitter grant of certification. The final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed.

The end user manual shall include all required regulatory information/warning as shown in this manual, including: This product must be installed and operated with a minimum distance of 20 cm between the radiator and user body.

This device have got a FCC ID: 2ANDL-WB3L. The final end product must be labeled in a visible area with the following: "Contains Transmitter Module FCC ID:2ANDL-WB3L"

This device is intended only for OEM integrators under the following conditions:

1) The antenna must be installed such that 20cm is maintained between the antenna and users, and

2) The transmitter module may not be co-located with any other transmitter or antenna.

As long as 2 conditions above are met, further transmitter test will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

Declaration of Conformity European notice



Hereby, Hangzhou Tuya Information Technology Co., Ltd declares that this module product is in compliance with essential requirements and other relevant provisions of Directive 2014/53/EU, 2011/65/EU. A copy of the Declaration of conformity can be found at <https://www.tuya.com>



This product must not be disposed of as normal household waste, in accordance with EU directive for waste electrical and electronic equipment (WEEE- 2012/19/EU). Instead, it should be disposed of by returning it to the point of sale, or to a municipal recycling collection point.

The device could be used with a separation distance of 20cm to the human body.